## Comparative Study of Al<sub>2</sub>O<sub>3</sub> and HfO<sub>2</sub> as Gate Dielectric on AlGaN/GaN Metal Oxide Semiconductor High-Electron Mobility Transistors

Authors : Kaivan Karami, Sahalu Hassan, Sanna Taking, Afesome Ofiare, Aniket Dhongde, Abdullah Al-Khalidi, Edward Wasige Abstract : We have made a comparative study on the influence of  $Al_2O_3$  and  $HfO_2$  grown using atomic layer deposition (ALD) technique as dielectric in the AlGaN/GaN metal oxide semiconductor high electron mobility transistor (MOS-HEMT) structure. Five samples consisting of 20 nm and 10 nm each of  $Al_2O_3$  and  $HfO_2$  respectively and a Schottky gate HEMT, were fabricated and measured. The threshold voltage shifts towards negative by 0.1 V and 1.8 V for 10 nm thick  $HfO_2$  and 10 nm thick  $Al_2O_3$  gate dielectric layers respectively. The negative shift for the 20 nm  $HfO_2$  and 20 nm  $Al_2O_3$  were 1.2 V and 4.9 V respectively. Higher gm/IDS (transconductance to drain current) ratio was also obtained in  $HfO_2$  than  $Al_2O_3$ . With both materials as dielectric, a significant reduction in the gate leakage current in the order of  $10^4$  was obtained compared to the sample without the dielectric material.

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